			-	<del>+-</del>		
Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S14 2	1467	257/750.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 10:56
S14 3	72	contact pad and S142	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 12:42
S14 4	59	(circuit same signal same process\$4) and S142	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 15:50
S14 6	866	(bump or pad or via) and S142	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 18:28
S14 7	2	S146 and subtrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ .	ON	2007/01/22 12:45
S14 9	. 843	S146 and layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 12:47
S15 0	8	S149 and intergrated circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 12:47
S15 1		"5719448".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ ·	ON	2007/01/22 17:31

S15 2	11086	(intergrated circuit or IC) and multi-layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ .	ON	2007/01/22 17:32
S15 3	10434	S152 and (contact\$3 or pad\$2 or via or bump or connect\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 17:36
S15 4	9569	257/693,773,774,780,781,752,750. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 17:37
S15 5	248	S153 and S154	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 12:37
S15 6	2	"5281855".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ .	ON	2007/01/22 18:24
S15 7	45725	second same protective same layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 18:27
S15 8	<b>5586</b> .	S157 and integrated circuit\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ .	ON	2007/01/22 18:27
S15 9	1	(bump or pad or via) and S148	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/22 18:28

1/24/2007 1:25:16 PM Page C:\Documents and Settings\ttran5\My Documents\EAST\Workspaces\package\integrated circuit with at least one bump.wsp Page 2

S16 0	. 0	"4484215,7084496,5426072".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 12:38
S16 1	0	"4484215,7084496,5426072"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 12:40
S16 2	30	"4484215"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 12:40
S16 3	2	"4484215".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 12:41
S16 4	2	"7084496".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 12:45
S16 5		"5426072".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 12:41
S16 6	2	"6313537".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 12:46
S16 7	6	("5248903"   "5404047"   "5502337"   "5736791"   "5739587"   "5751065").PN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/01/23 12:51
S16 8	6	("5248903"   "5404047"   "5502337"   "5736791"   "5739587"   "5751065").PN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/01/23 12:52

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S16 9	6	("5248903"   "5404047"   "5502337"   "5736791"   "5739587"   "5751065").PN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/01/23 15:18
S17 0	0	scheucher meimo.in.	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/01/23 15:18
S17 1	3	scheucher heimo.in.	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/01/23 15:19
S17 2	48	"5751065"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/01/23 17:07
S17 3	2	"5751065".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON ·	2007/01/23 17:07

1/24/2007 1:25:16 PM Page C:\Documents and Settings\ttran5\My Documents\EAST\Workspaces\package\integrated circuit with at least one bump.wsp Page 4

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	·2386	257/693,773,774,780,781,752,750, 713,200.ccls.	US-PGPUB	ADJ	ON	2007/01/24 14:04
L9		(integrated circuit or IC) and substrate and (signal near5 processing near5 circuit) and (contact pad or contact via or bump or via) and boundary face and (protective lay\$4 or dielectric lay\$4) and (height same "15") and (ring or round or circle or enclosed form) and (width same ("2" or two) same ("15" or fifteen))	US-PGPUB	ADJ	ON	2007/01/24 15:23
L10	1	(integrated circuit or IC) and substrate and (signal near5 processing near5 circuit) and (contact pad or contact via or bump or via) and boundary face and (protective lay\$4 or dielectric lay\$4) and (height same "15") and (ring or round or circle or enclosed form) and (width same ("2" or two) same ("15" or fifteen)).clm.	US-PGPUB	ADJ	ON .	2007/01/24 15:23
L11	1	I10 and I7	US-PGPUB	, ADJ	ON -	2007/01/24 15:24